

NEI	Work Instruction		Page 1 of 14
Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-0068-00	By: Tim Connolly	Current Rev: 0A	Date: 2/03/09
Assemblies Covered: C-1500 (786-0068-XX)			

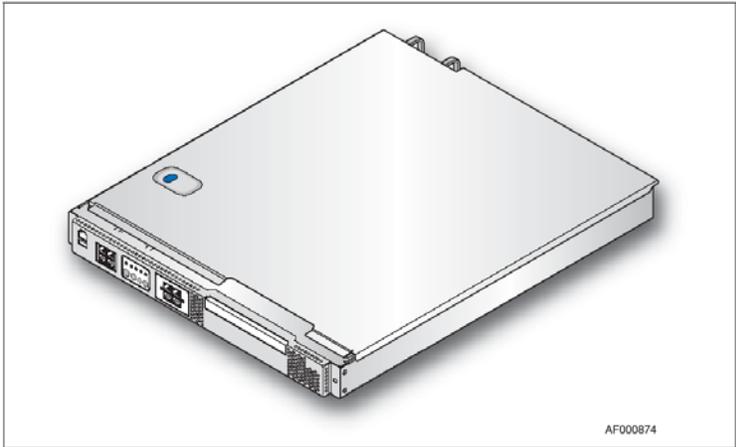
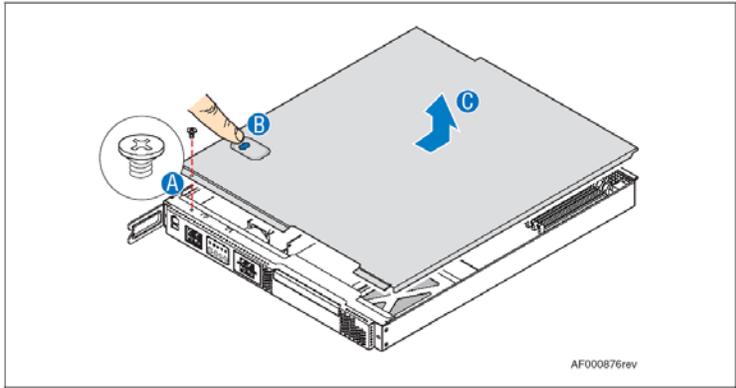
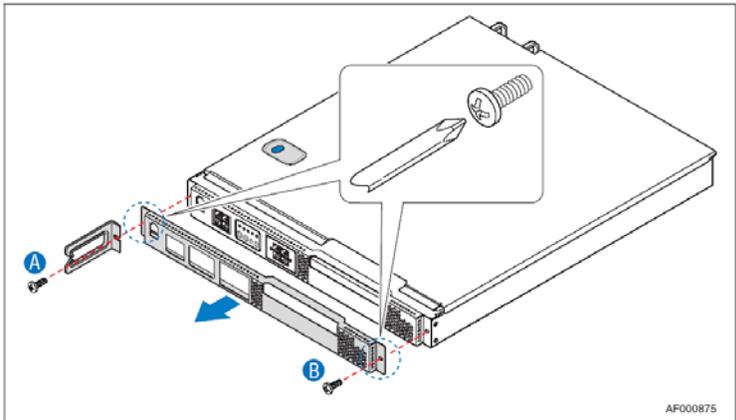


Revision	Date	ECO #	Revised By	Description of Changes
0A			Tim Connolly	Original Release
0B	7/20/2010		Thinh Ta	

Tools Required:

- #2 Phillips Screwdriver
- #1 Phillips Screwdriver

NEI	Work Instruction		Page 2 of 14
Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-0068-00	By: Tim Connolly	Current Rev: 0A	Date: 2/03/09
Assemblies Covered: C-1500 (786-0068-XX)			

1.	<p>Removal of the power cord(s) does not require any tools</p> <ol style="list-style-type: none"> a. Remove the power cord(s) first. 	 <p>AF000874</p>
2.	<p>Removal of the top access cover needs a #2 Philips screwdriver.</p> <ol style="list-style-type: none"> a. Remove the shipping screw from the front of the chassis left side (“A”). b. While holding the blue button at the top of the chassis in (“B”), slide the top cover back until it stops (“C”). c. Lift the cover straight up to remove it from the server. d. Discard sheet metal cover and screw in appropriate recycle bin. 	 <p>AF000876rev</p>
3.	<p>Removal of the bezel (if present) requires a #2 Phillips screwdriver.</p> <ol style="list-style-type: none"> a. Remove the left-side screw and cable management arm, if installed. (“A”). b. Remove the right-side screw to release the bezel. (“B”) c. Lift the front bezel from the chassis. d. Discard the metal rails and screws in the appropriate recycle bin. 	 <p>AF000875</p>

Title:

Unit Disassembly for WEEE

Document Number / Disk File:

597-786-0068-00

By:

Tim Connolly

Current Rev:

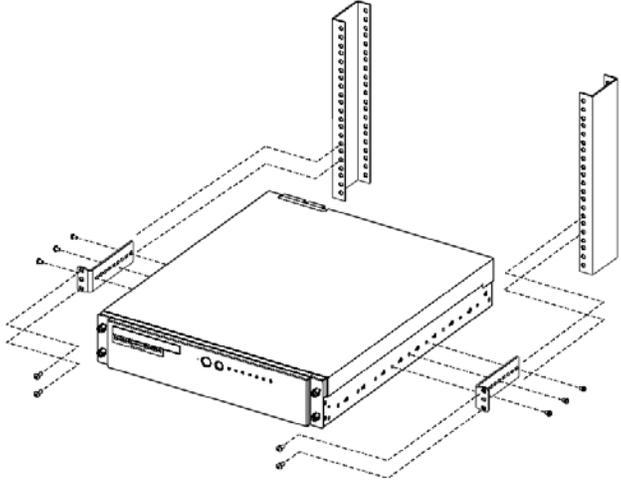
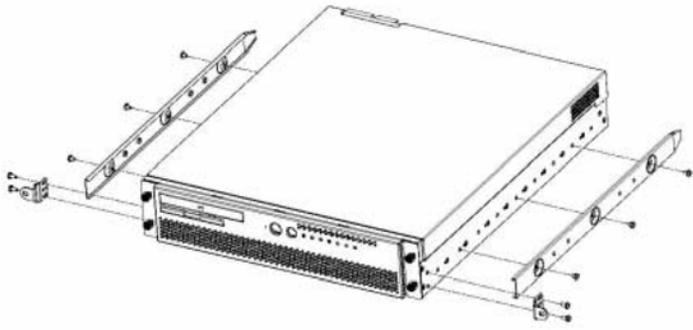
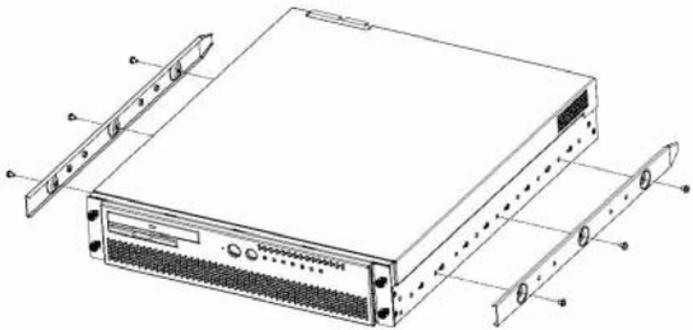
0A

Date:

2/03/09

Assemblies Covered:

C-1500 (786-0068-XX)

<p>4.</p>	<p>Removal of rack mount rails, if present, requires a #2 Philips screwdriver.</p> <p>If the TMLCMOUNT21 kit (19" 2 post rack mount) is installed:</p> <ol style="list-style-type: none"> Remove the three screws on each side to release the mounting brackets. Discard the Mounting Brackets and screws in the appropriate recycle bin. 	
<p>4.</p>	<p>If the TMLPMOUNT41 kit (19" 2-Post and 4-Post racks) is installed:</p> <ol style="list-style-type: none"> Remove the two screws holding the front bracket to the chassis. Remove the three screws on each side to release the mounting rails. Discard the Brackets, Mounting Rails, and screws in the appropriate recycle bin. 	
<p>4.</p>	<p>If the TMLPMOUNT42 kit (23" 2-Post and 4-Post racks) is installed:</p> <ol style="list-style-type: none"> Remove the three screws on each side to release the mounting rails. Discard the Mounting Rails and screws in the appropriate recycle bin. 	

Title:

Unit Disassembly for WEEE

Document Number / Disk File:

597-786-0068-00

By:

Tim Connolly

Current Rev:

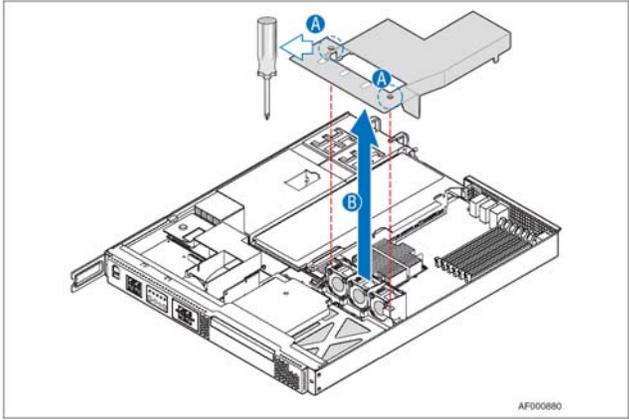
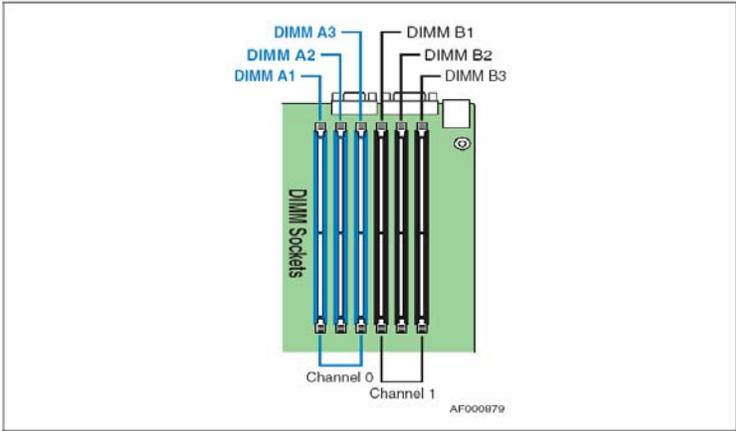
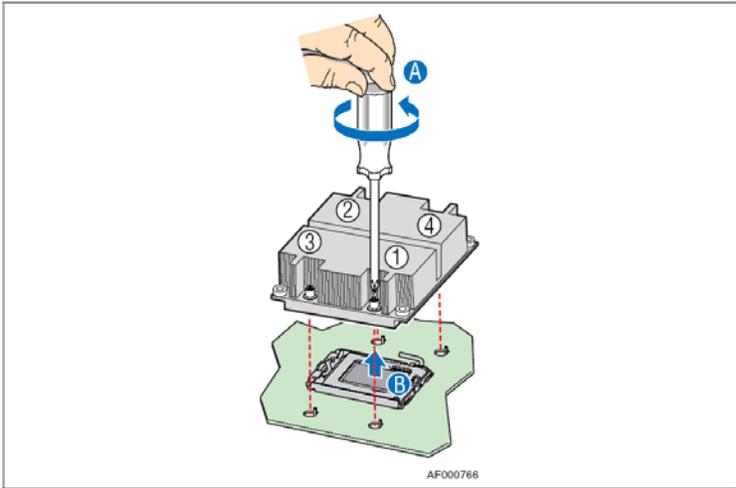
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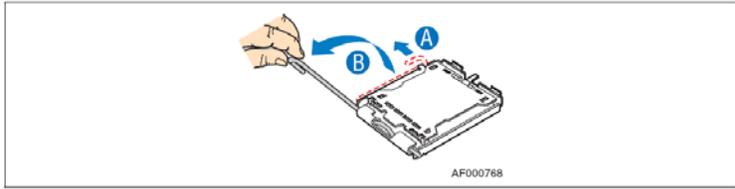
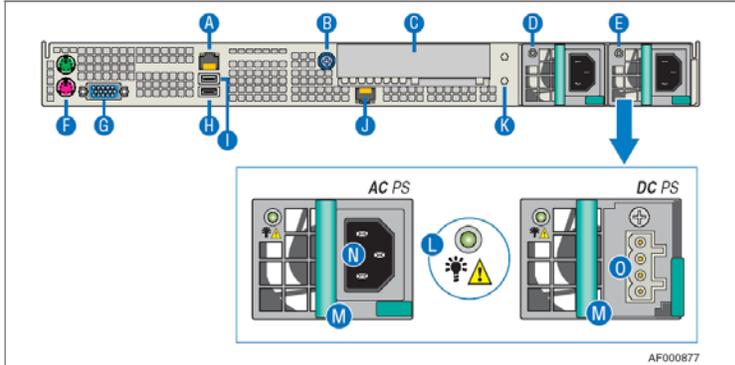
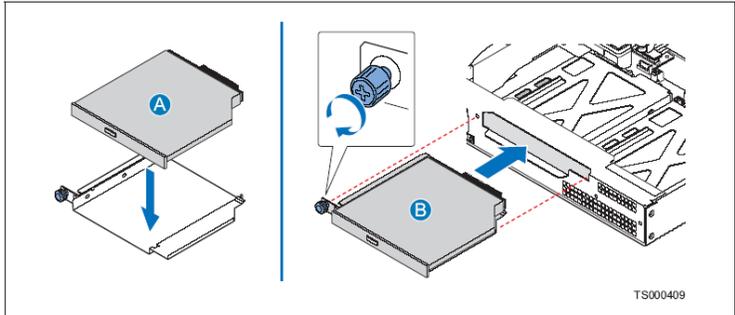
2/03/09

Assemblies Covered:

C-1500 (786-0068-XX)

5.	<p>Removal of the Processor Air Duct requires a #2 Philips screwdriver.</p> <ol style="list-style-type: none"> Remove the screws at the top of the air duct (“A”). Lift the air duct from the server platform (“B”). Discard the Processor Air Duct and screws in the appropriate recycle bin. 	 <p>AF000880</p>
6.	<p>Removal of the Memory DIMM(s) does not require any tools.</p> <ol style="list-style-type: none"> Open the DIMM socket levers by pushing down on them. Holding the DIMM by the edges, lift it away from the socket. Discard the Memory DIMM(s) in the appropriate recycle bin. 	 <p>AF000879</p>
7.	<p>Removal of the Processor Heat sink requires a #2 Philips screwdriver.</p> <ol style="list-style-type: none"> Loosen the four captive screws on the corners of the heat sink with a #2 Phillips screwdriver. (“A”). Twist the heat sink slightly to break the seal between the heat sink and the processor. (“B”) Lift the heat sink from the processor. If it does not pull up easily, twist the heat sink again. Discard the Processor Heat sink in the appropriate recycle bin. 	 <p>AF000766</p>

NEI	Work Instruction		Page 5 of 14
Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-0068-00	By: Tim Connolly	Current Rev: 0A	Date: 2/03/09
Assemblies Covered: C-1500 (786-0068-XX)			

<p>8.</p>	<p>Removal of the Processor does not require any tools.</p> <ol style="list-style-type: none"> Open the socket by pushing the lever handle down and away from the socket to release it. (“A” and “B”) Pull the lever and open the load plate all the way. Lift the processor from the socket. Discard the Processor in the appropriate recycle bin. 	
<p>9.</p>	<p>Removal of the Power Supply(ies) does not require any tools.</p> <ol style="list-style-type: none"> Press and hold the green safety lock to the left to disengage the power supply. Grasp the handle and pull the power supply from the chassis. (“M”) Discard the Power Supply(ies) in the appropriate recycle bin. 	
<p>10.</p>	<p>Removal of the Optical Device Tray Assembly requires a #2 Philips screwdriver.</p> <ol style="list-style-type: none"> Loosen the thumbscrew securing the Optical Device Tray to the chassis. Unplug the Power and IDE cables from the rear of the optical device. Pull the optical device straight out of the chassis. Use no tool to separate the Optical Device and the tray. Discard the optical drive tray and screw in the appropriate recycle bin. 	

Title:

Unit Disassembly for WEEE

Document Number / Disk File:

597-786-0068-00

By:

Tim Connolly

Current Rev:

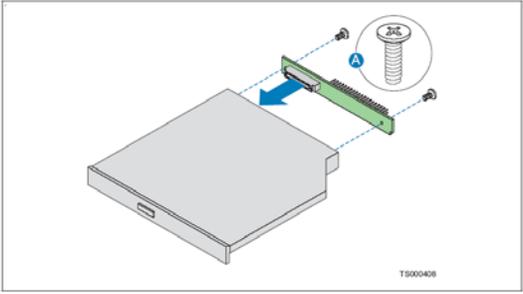
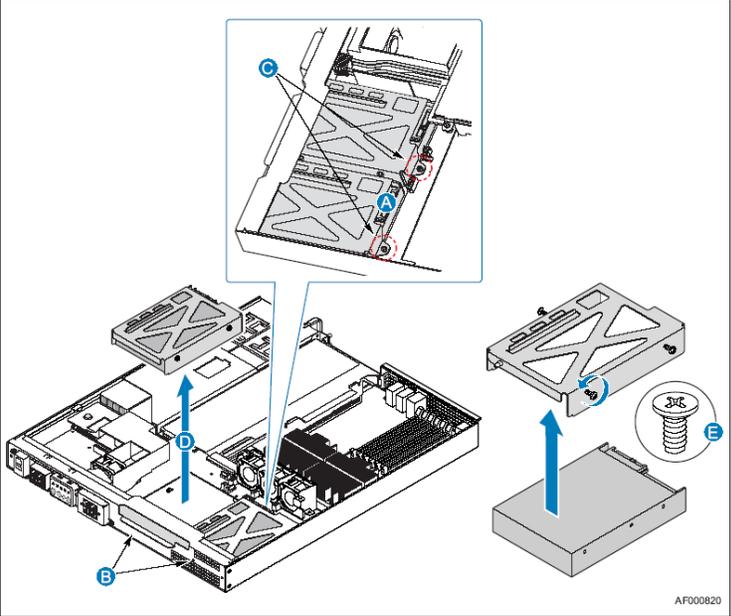
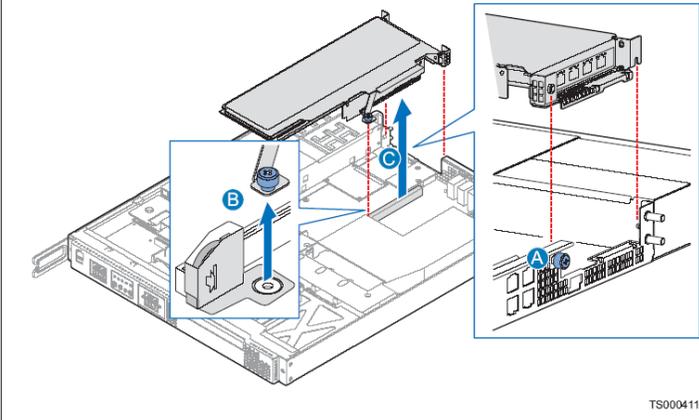
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Date:

2/03/09

Assemblies Covered:

C-1500 (786-0068-XX)

11.	<p>Removal of the Interposer Board requires a #1 Philips screwdriver.</p> <ol style="list-style-type: none"> Remove the two screws securing the board to the back of the optical device. Pull the board away from the device to complete the removal Discard the Interposer Board, Optical Device, and screws in the appropriate recycle bin. 	
12.	<p>Removal of the Drive Tray Assembly requires a #2 Philips screwdriver.</p> <ol style="list-style-type: none"> Unplug the cable from the rear of the drive assembly ("A"). Loosen the captive screw at the rear of the drive tray assembly ("C"). Remove the front panel screw that secures the drive tray assembly. ("B") Remove the drive tray from the chassis by sliding it rearward and lifting up. ("D") Loosen the three screws holding the drive to the tray, and lift the tray off the drive. Discard the Drive Tray Assembly, Hard Drive, and screws in the appropriate recycle bin. 	
13.	<p>Removal of the PCI Riser Card Assembly requires a #2 Phillips screwdriver.</p> <ol style="list-style-type: none"> Loosen the blue captive screw that secures the riser card assembly to the server board. ("A") Loosen the blue captive thumb screw on the rear panel of the chassis. ("B") Lift the riser card assembly straight up and remove it from the chassis. ("C") 	

Title:

Unit Disassembly for WEEE

Document Number / Disk File:

597-786-0068-00

By:

Tim Connolly

Current Rev:

0A

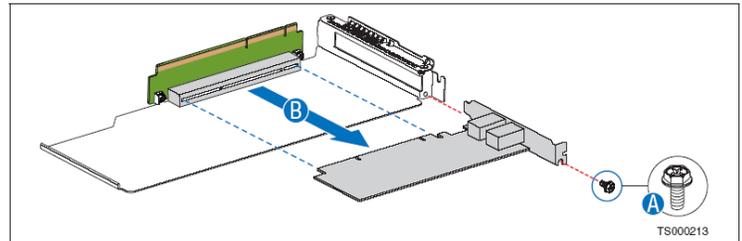
Date:

2/03/09

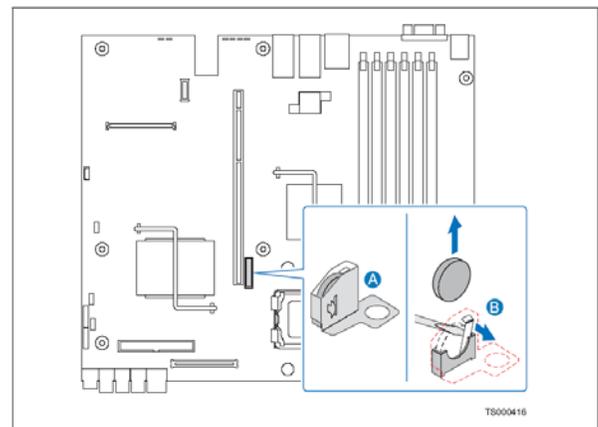
Assemblies Covered:

C-1500 (786-0068-XX)

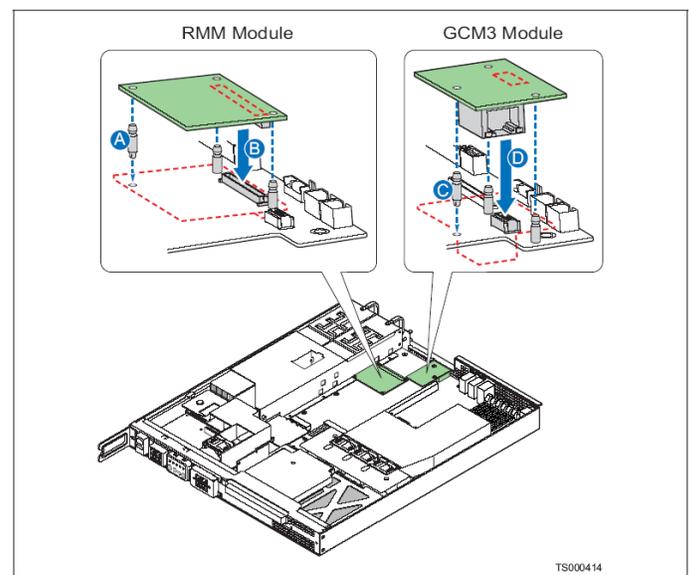
14. Removal of the PCI card, if present, from the Riser Card Assembly requires a #2 Philips screwdriver.
- Turn the riser card assembly upside-down to remove the PCI card.
 - Remove the rear retention screw from the riser card. ("A")
 - Detach the PCI card from the riser card connector. ("B")
 - Discard the PCI card and screw in the appropriate Recycle Bin.**



15. Removal of the Battery from the motherboard does not require any tools.
- Remove the coin style Lithium Battery.
 - Discard the Lithium Battery in the appropriate recycle bin.**
- *** CAUTION *****
- Care should be observed when disposing of the battery to avoid shorting it!**



16. Removal of the RMM and/or GCM3 Module(s), if present, does not require any tools.
- Grasp the module by the side of the board, and pull the board straight up until the standoffs disengage. Repeat if another module is installed.
 - Discard the RMM and/or GCM3 in the appropriate recycle bin.**



Title:

Unit Disassembly for WEEE

Document Number / Disk File:

597-786-0068-00

By:

Tim Connolly

Current Rev:

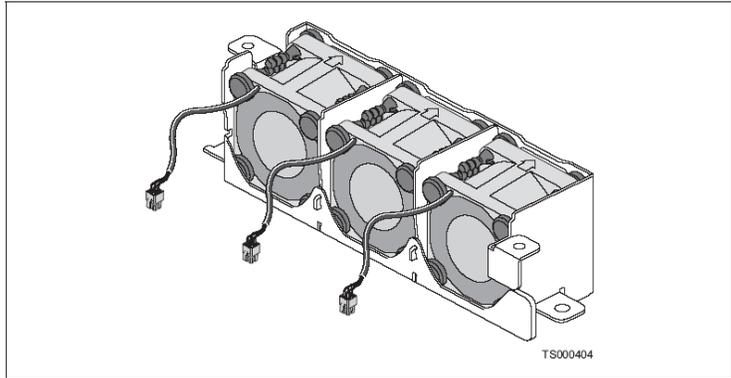
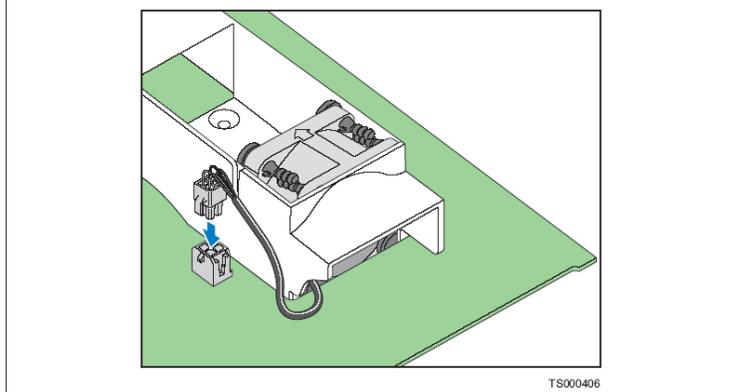
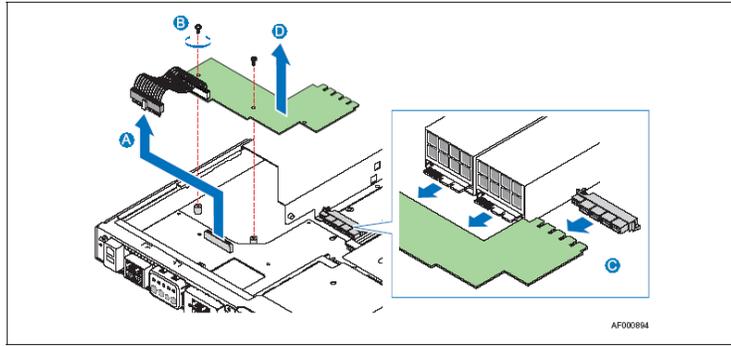
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Date:

2/03/09

Assemblies Covered:

C-1500 (786-0068-XX)

17.	<p>Removal of the CPU Fans requires a #2 Philips screwdriver.</p> <ol style="list-style-type: none"> Disconnect the fan power connectors from the motherboard. Unscrew a screw securing the fan bracket to the chassis, and lift the fan bracket out of the chassis. Unscrew all 6 screws the hold three fans to the fan bracket. Discard the CPU Fans, CPU Fan Bracket, and screws in the appropriate recycle bin. 	
18.	<p>Removal of the PCI Fan Tray requires a #2 screwdriver.</p> <ol style="list-style-type: none"> Unplug the PCI fan power cable from the EFP board. Unscrew two screws that securing the PCI fan tray to the chassis. Unscrew two top screws that securing the fan to the PCI fan tray. Remove the fan from the PCI fan tray. Discard the fan, the PCI fan tray, and screw(s) in the appropriate recycle bin. 	
19.	<p>Removal of the Power Distribution Board requires a #2 Philips screwdriver.</p> <ol style="list-style-type: none"> Unscrew the fastening screws. ("A") Disconnect the EFP power cable on the EFP board and gently pull the PDB away from the power supply connectors and the server board power connector. ("B") Lift the power distribution board from the chassis ("C"). Discard the Power Distribution Board and screws in the appropriate recycle bin. 	

Title:

Unit Disassembly for WEEE

Document Number / Disk File:

597-786-0068-00

By:

Tim Connolly

Current Rev:

0A

Date:

2/03/09

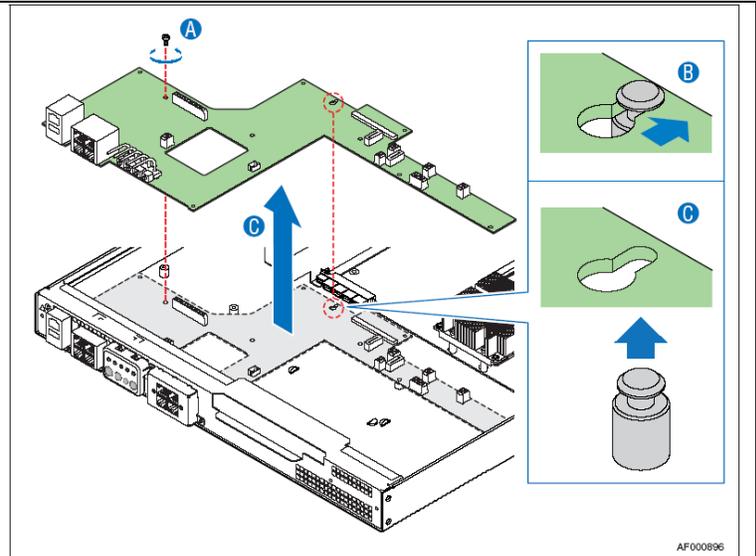
Assemblies Covered:

C-1500 (786-0068-XX)

20. Removal of the Ethernet Front Panel Board (EFP Board) requires a #2 Philips screwdriver.

- Disconnect any cables attached to the EFP Board.
- Gently work the EFP board backward ("B"), toward the rear of the chassis to disengage the light pipe assembly from behind the front control panel bezel.
- Pull the front panel I/O board up over the placement pegs ("C") and lift it from the chassis.

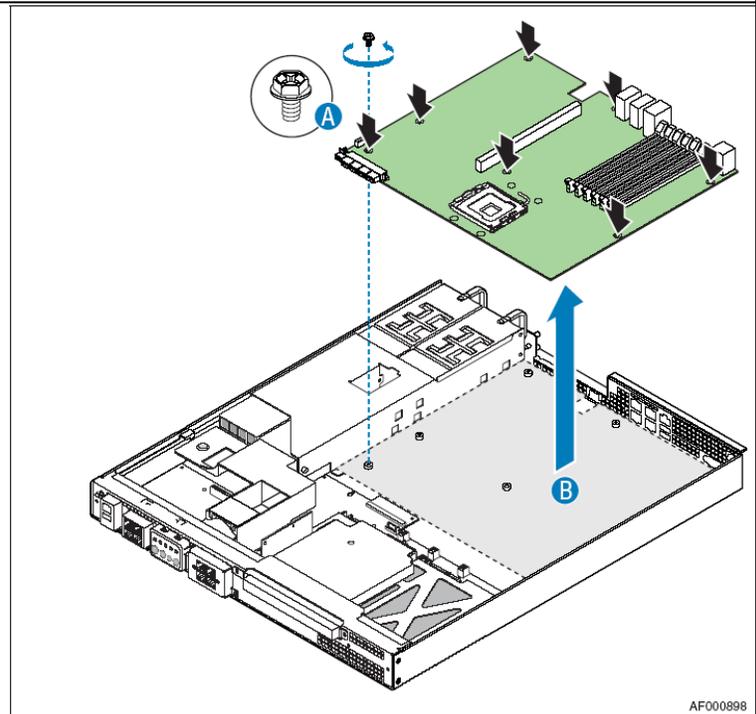
d. Discard the EFP Board and screw in the appropriate recycle bin.



21. Removal of the Server Board requires a #2 Philips screwdriver.

- Disconnect any cables from the server board.
- Remove the seven screws that attach the server board to the chassis. ("A")
- Tilt the server board and lift it from the chassis. Use caution in pulling it out from beneath the rear panel.

d. Discard the Server Board, cables, and screws in the appropriate recycle bin.



Title:

Unit Disassembly for WEEE

Document Number / Disk File:
597-786-0068-00

By:
Tim Connolly

Current Rev:
0A

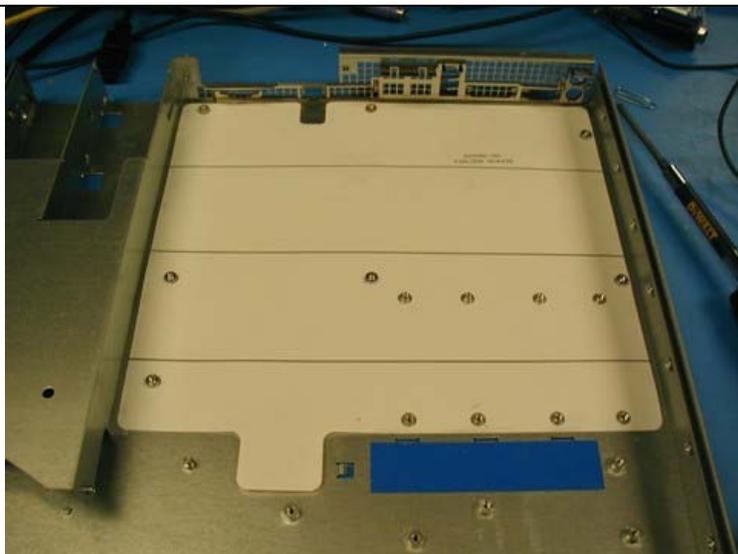
Date:
2/03/09

Assemblies Covered:

C-1500 (786-0068-XX)

22. Removal of the Motherboard insulator requires no tool.

Discard the insulator in the appropriate recycle bin.



Fully Disassembled Unit

Title:

Unit Disassembly for WEEE

Document Number / Disk File:
597-786-0068-00

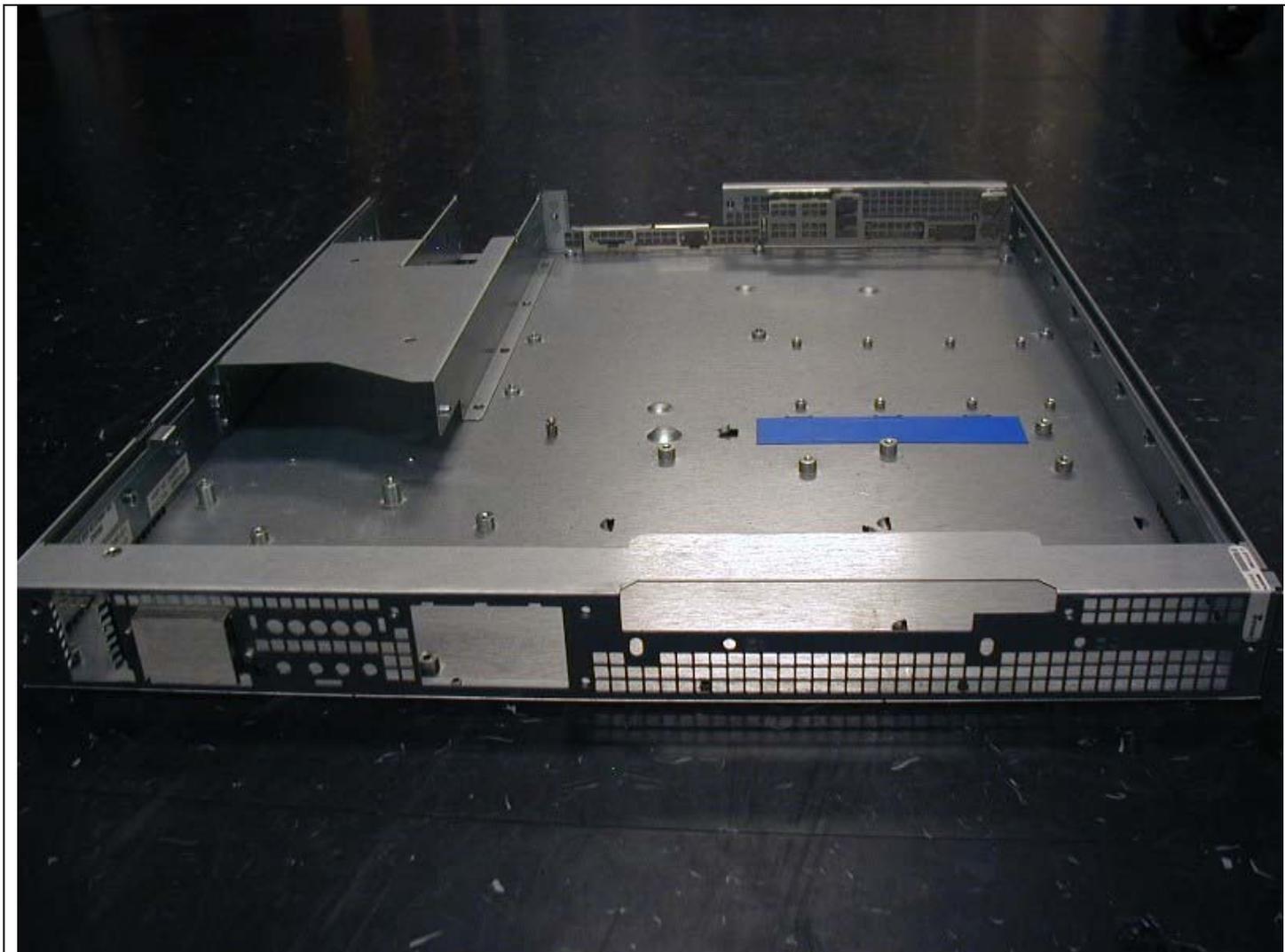
By:
Tim Connolly

Current Rev:
0A

Date:
2/03/09

Assemblies Covered:

C-1500 (786-0068-XX)



NEI	Work Instruction		Page 12 of 14
Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-0068-00	By: Tim Connolly	Current Rev: 0A	Date: 2/03/09
Assemblies Covered: C-1500 (786-0068-XX)			

Recycling/Material Code	Important Information
Material /Components, which must be removed and treated separately	
Lithium Battery	Battery free of hazardous substances, installed in socket on the motherboard
Printed circuit boards	Motherboard, DIMMs, Gigabit card, PCI riser boards, Power Supply, CD-ROM adapter board, & LED Board
Disk Drives	Mounted on disk carrier
Material /Components, which can disturb certain recycling processes	
Copper	Fan sink
Material /Components, through which benefits can normally be achieved	
Cold Rolled Steel	Access cover, chassis bottom, CD-ROM and Hard Drive bracket, fan tray, & Card Cage
* ABS	Shroud
Cables	Distributed in device
Fans	Fan tray
Special notes	
* Flame retardant of plastics does not contain PBB and PBDE.	

NEI	Work Instruction	Page 13 of 14	
Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-0068-00	By: Tim Connolly	Current Rev: 0A	Date: 2/03/09
Assemblies Covered: C-1500 (786-0068-XX)			

Annex A

Producer:	<Company name, other on addressing the producer>
Scope of information sheet:	< Product category as in Annex IA of WEEE Directive, or type of equipment as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >

Component or Material	Remarks / Location
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/ Other	Lithium battery ↓ Located on the motherboard
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	NONE
Mercury (Hg) in other applications**	NONE
Cadmium**	NONE
Gas discharge lamps	NONE
Plastic containing ruminated flame retardants other than in Printed Circuit Assemblies ***	NONE
Liquid Crystal Displays with a surface greater than 100 cm ²	NONE
Capacitors with PCB's	NONE
Capacitors with substances of concern**** + height > 25 mm, diameter > 25 mm or proportionately similar volume	NONE
Asbestos	NONE
Refractory ceramic fibres	NONE
Radio-active substances	NONE
Beryllium Oxide	NONE
Other forms of Beryllium	BE-CU in some connector ↓ contacts
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC).	NONE
Components with pressurised gas which need special attention (Pressure > 1,5 bar) *****	NONE
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil...)	NONE
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts which need special attention ***** (diameter > 10 mm and height > 25 mm or proportionally similar volume and expanding)	NONE
PBDE (deca- & octa-BDE) and Perfluorocatane sulfantes (PFOS) in Directive 2006/122/EC	NONE

NEI	Work Instruction		Page 14 of 14
Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-0068-00	By: Tim Connolly	Current Rev: 0A	Date: 2/03/09
Assemblies Covered: C-1500 (786-0068-XX)			

↓ = Arrow indicates the need for the location of the compartment/ substances within the product. When the location of a substance/ components is requested, it is at part level, e.g. main board, housing etc

* Internal means that batteries can only be removed by opening the product by means of (a) tool(s).

** Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95 (EC) (RoHS Directive) or if their use is permitted through exemptions in the Annex of Directive 2002/95(EC)

*** To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weight more than 25 g.

**** Substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments

***** Needs of equivalent nature as those for maintenance, service manuals and installation for safety purposes.